# **Amplifier Transistors**

# **NPN Silicon**

#### **Features**

• These are Pb-Free Devices

#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Collector - Emitter Voltage	V <sub>CEO</sub>	45	Vdc
Collector - Base Voltage	V <sub>CBO</sub>	50	Vdc
Emitter – Base Voltage	V <sub>EBO</sub>	5.0	Vdc
Collector Current - Continuous	Ic	800	mAdc
Total Device Dissipation @ T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	625 5.0	mW mW/°C
Total Device Dissipation @ T <sub>C</sub> = 25°C Derate above 25°C	P <sub>D</sub>	1.5 12	W mW/°C
Operating and Storage Junction Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

#### THERMAL CHARACTERISTICS

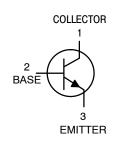
Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	200	°C/W
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	83.3	°C/W

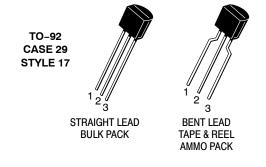
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



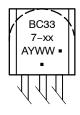
## ON Semiconductor®

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#### **MARKING DIAGRAM**



BC337-xx = Device Code

(Refer to page 4)

A = Assembly Location

Y = Year
WW = Work Week
= Pb-Free Package

(Note: Microdot may be in either location)

# **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS	·				
Collector – Emitter Breakdown Voltage ( $I_C = 10 \text{ mA}, I_B = 0$ )	V <sub>(BR)CEO</sub>	45	-	_	Vdc
Collector – Emitter Breakdown Voltage ( $I_C$ = 100 $\mu$ A, $I_E$ = 0)	V <sub>(BR)CES</sub>	50	-	-	Vdc
Emitter – Base Breakdown Voltage ( $I_E = 10 \ \mu A, \ I_C = 0$ )	V <sub>(BR)EBO</sub>	5.0	-	-	Vdc
Collector Cutoff Current (V <sub>CB</sub> = 30 V, I <sub>E</sub> = 0)	I <sub>CBO</sub>	-	-	100	nAdc
Collector Cutoff Current (V <sub>CE</sub> = 45 V, V <sub>BE</sub> = 0)	I <sub>CES</sub>	-	-	100	nAdc
Emitter Cutoff Current (V <sub>EB</sub> = 4.0 V, I <sub>C</sub> = 0)	I <sub>EBO</sub>	-	-	100	nAdc
ON CHARACTERISTICS	·				
BC3	h <sub>FE</sub> BC337 37-25 37-40	100 160 250 60	- - -	630 400 630	-
Base–Emitter On Voltage (I <sub>C</sub> = 300 mA, V <sub>CE</sub> = 1.0 V)	V <sub>BE(on)</sub>	-	-	1.2	Vdc
Collector – Emitter Saturation Voltage (I <sub>C</sub> = 500 mA, I <sub>B</sub> = 50 mA)	V <sub>CE(sat)</sub>	-	-	0.7	Vdc
SMALL-SIGNAL CHARACTERISTICS					
Output Capacitance (V <sub>CB</sub> = 10 V, I <sub>E</sub> = 0, f = 1.0 MHz)	C <sub>ob</sub>	-	15	_	pF
Current – Gain – Bandwidth Product (I <sub>C</sub> = 10 mA, V <sub>CE</sub> = 5.0 V, f = 100 MHz)	f <sub>T</sub>	-	210	-	MHz

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

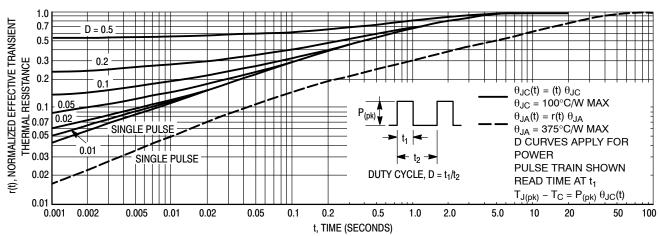


Figure 1. Thermal Response

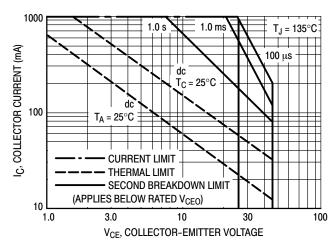


Figure 2. Active Region - Safe Operating Area

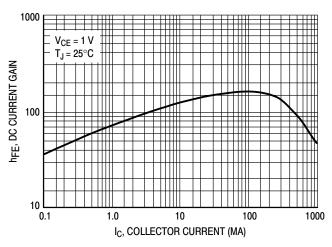


Figure 3. DC Current Gain

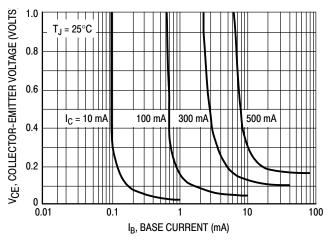


Figure 4. Saturation Region

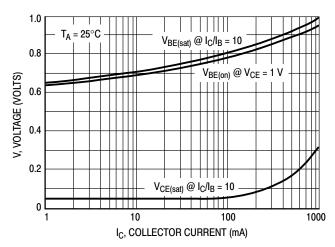


Figure 5. "On" Voltages

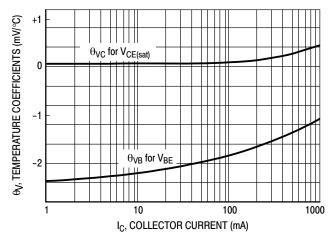


Figure 6. Temperature Coefficients

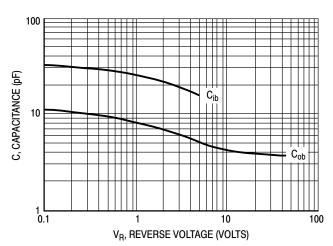


Figure 7. Capacitances

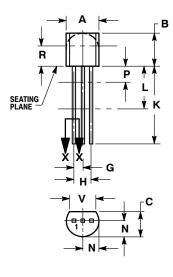
### **ORDERING INFORMATION**

Device	Marking	Package	Shipping <sup>†</sup>
BC337G	7		5000 Units / Bulk
BC337RL1G	7	TO-92 (Pb-Free)	2000 / Tape & Reel
BC337-025G	7–25		5000 Units / Bulk
BC337-25RL1G	7–25		2000 / Tape & Reel
BC337-25RLRAG	7–25		2000 / Tape & Reel
BC337-25ZL1G	7–25		2000 / Ammo Box
BC337-040G	7–40		5000 Units / Bulk
BC337-40RL1G	7–40		2000 / Tape & Reel
BC337-40ZL1G	7–40		2000 / Ammo Box

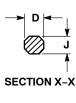
<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### PACKAGE DIMENSIONS

TO-92 (TO-226) CASE 29-11 ISSUE AM

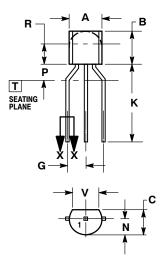


STRAIGHT LEAD **BULK PACK** 



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: INCH.
- CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
- LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.175	0.205	4.45	5.20
В	0.170	0.210	4.32	5.33
C	0.125	0.165	3.18	4.19
D	0.016	0.021	0.407	0.533
G	0.045	0.055	1.15	1.39
Н	0.095	0.105	2.42	2.66
7	0.015	0.020	0.39	0.50
K	0.500		12.70	
L	0.250		6.35	
N	0.080	0.105	2.04	2.66
Р		0.100		2.54
R	0.115		2.93	
V	0 135		3 43	l



BENT LEAD TAPE & REEL AMMO PACK



#### NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: MILLIMETERS. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
- LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

	MILLIMETERS		
DIM	MIN	MAX	
Α	4.45	5.20	
В	4.32	5.33	
С	3.18	4.19	
D	0.40	0.54	
G	2.40	2.80	
J	0.39	0.50	
K	12.70		
N	2.04	2.66	
P	1.50	4.00	
R	2.93		
٧	3.43		

PIN 1. COLLECTOR BASE

**EMITTER** 

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